

## ABSTRACT OF THE DISCLOSURE

### INTEGRATED CIRCUIT INCLUDING SILICON WAFER WITH ANNEALED GLASS PASTE

An integrated circuit (IC) package comprises an IC wafer and an annealed glass paste (AGP) layer that is arranged adjacent to the IC wafer. A molding material encapsulates at least part of the IC wafer and the AGP layer. The AGP layer is arranged on at least one side of the IC wafer. The AGP layer is arranged on a plurality of disjoint areas on at least one side of the IC wafer. A layer of a conductive material is arranged on a portion of the AGP layer.

FIG. 27



\*162162\*



\*G00002\*